

APPLICANT'S INFORMATION
DISCLOSURE STATEMENT

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Applicant: Brodsky

Filing Date: Herewith 9/17/03

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U.S. PATENT DOCUMENTS

Initial*		Document No.	Date	Name	Class	Subcl.	Filing Date
BS	AA	4,988,306	01/29/91	Hopfer, III et al	439	66	05/16/89
BS	AB	5,122,067	06/16/92	Sunne	439	91	05/23/91
BS	AC	5,599,193	02/04/97	Crotzer	439	66	08/23/94
BS	AD	5,650,919	07/22/97	Loh et al	361	779	02/21/96
BS	AE	5,720,630	02/24/98	Richmond et al	439	591	02/26/96
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BS	AG	5,899,757	05/04/99	Neidich et al	439	67	11/03/97
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FOREIGN REFERENCES

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OTHER DOCUMENTS

	AO	IBM Technical Disclosure Bulletin, January, 1993, "Button Contacts for Probe Card Applications", pp. 186-187
BS	AP	IBM Technical Disclosure Bulletin, March, 1991, "Pluggable/Removable Cube of Chips Packaging Method", pp. 459-460
	AQ	
	AR	
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Examiner: Neuenschwander Date Considered: 4/25/05

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if in conformance and not considered. Include copy of this form with next communication to applicant.